

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A card comprising:
a display device comprising a first semiconductor element comprising a first polycrystalline semiconductor film;
a first thin film integrated circuit comprising a second semiconductor element comprising a second polycrystalline semiconductor film;
a first substrate; and
a second substrate,
wherein the display device is electrically connected to the first thin film integrated circuit,
wherein the thin film integrated circuit and the display device are covered and sealed with a resin between the first substrate and the second substrate of the card, and
wherein the first substrate and the second substrate comprise a plastic material.
2. (Original) A card according to claim 1, wherein the card has a thickness from 0.05 mm through 1.5 mm.
3. (Previously Presented) A card according to claim 1, wherein the display device is a passive matrix type display device.
4. (Original) A card according to claim 1, wherein the display device is an active matrix type.

5. (Previously Presented) A card according to claim 1, further comprising:
a second thin film integrated circuit,
wherein the first and second thin film integrated circuits are laminated.

6.-8. (Canceled)

9. (Previously Presented) A card according to claim 1, wherein the display
device is a liquid crystal display device.

10. (Canceled)

11. (Previously Presented) A card according to claim 1, wherein the display
device is a light emitting device.

12. (Canceled)

13. (Previously Presented) A card according to claim 1, wherein the card is an
ID card.

14. (Canceled)

15. (Previously Presented) A card according to claim 1, wherein the card is a
semi-hard card.

16. (Canceled)

17. (Previously Presented) A card according to claim 1, wherein the card is an IC card.

18.-19. (Canceled)

20. (New) A card comprising:

a first substrate comprising a plastic material;

a display device comprising a first semiconductor element comprising a first polycrystalline semiconductor film over the first substrate;

a thin film integrated circuit comprising a second semiconductor element comprising a second polycrystalline semiconductor film over the first substrate;

a resin over the display device and the thin film integrated circuit; and

a second substrate comprising a plastic material over the resin.